


### Features

- Package fully compatible with the industry standard INT-A-pak power modules series
- High thermal conductivity package, electrically insulated case
- Excellent power volume ratio
- 4000 V<sub>RMS</sub> isolating voltage
- UL E78996 approved 
- TOTALLY LEAD-FREE

55 A  
90 A  
110 A

### Description

A range of extremely compact, encapsulated three phase controlled bridge rectifiers offering efficient and reliable operation. They are intended for use in general purpose and heavy duty applications.

### Major Ratings and Characteristics

Parameters	53MT.K 52MT.K 51MT.K	93MT.K 92MT.K 91MT.K	113MT.K 112MT.K 111MT.K	Units
I <sub>O</sub>	55	90	110	A
@ T <sub>C</sub>	85	85	85	°C
I <sub>FSM</sub> @ 50Hz	390	950	1130	A
@ 60Hz	410	1000	1180	A
I <sup>2</sup> t @ 50Hz	770	4525	6380	A <sup>2</sup> s
@ 60Hz	700	4130	5830	A <sup>2</sup> s
I <sup>2</sup> √t	7700	45250	63800	A <sup>2</sup> √s
V <sub>RRM</sub> range	800 to 1600			V
T <sub>STG</sub> range	-40 to 125			°C
T <sub>J</sub> range	-40 to 125			°C

**ELECTRICAL SPECIFICATIONS**

Voltage Ratings

Type number	Voltage Code	V <sub>RRM</sub> , maximum repetitive peak reverse voltage V	V <sub>RSM</sub> , maximum non-repetitive peak reverse voltage V	V <sub>DRM</sub> , max. repetitive peak off-state voltage gate open circuit V	I <sub>RRM</sub> /I <sub>DRM</sub> max. @ T <sub>J</sub> = 125°C mA
53/52/51MT..K	80	800	900	800	10
	100	1000	1100	1000	
	120	1200	1300	1200	
	140	1400	1500	1400	
	160	1600	1700	1600	
93/92/91MT..K 113/112/111MT..K	80	800	900	800	20
	100	1000	1100	1000	
	120	1200	1300	1200	
	140	1400	1500	1400	
	160	1600	1700	1600	

Forward Conduction

Parameter	53MT.K 52MT.K 51MT.K	93MT.K 92MT.K 91MT.K	113MT.K 112MT.K 111MT.K	Units	Conditions
I <sub>O</sub> Maximum DC output current @ Case temperature	55	90	110	A	120° Rect conduction angle
	85	85	85	°C	
I <sub>TSM</sub> Maximum peak, one-cycle forward, non-repetitive on state surge current	390	950	1130	A	t = 10ms No voltage reappplied
	410	1000	1180		t = 8.3ms
	330	800	950		t = 10ms 100% V <sub>RRM</sub> reappplied
	345	840	1000		t = 8.3ms
I <sup>2</sup> t Maximum I <sup>2</sup> t for fusing	770	4525	6380	A <sup>2</sup> s	t = 10ms No voltage reappplied
	700	4130	5830		t = 8.3ms
	540	3200	4510		t = 10ms 100% V <sub>RRM</sub> reappplied
	500	2920	4120		t = 8.3ms
I <sup>2</sup> √t Maximum I <sup>2</sup> √t for fusing	7700	45250	63800	A <sup>2</sup> √s	t = 0.1 to 10ms, no voltage reappplied
V <sub>T(TO)1</sub> Low level value of threshold voltage	1.17	1.09	1.04	V	(16.7% × π × I <sub>T(AV)</sub> < I < π × I <sub>T(AV)</sub> ), @ T <sub>J</sub> max.
V <sub>T(TO)2</sub> High level value of threshold voltage	1.45	1.27	1.27	V	(I > π × I <sub>T(AV)</sub> ), @ T <sub>J</sub> max.
r <sub>T1</sub> Low level value on-state slope resistance	12.40	4.10	3.93	mΩ	(16.7% × π × I <sub>T(AV)</sub> < I < π × I <sub>T(AV)</sub> ), @ T <sub>J</sub> max.
r <sub>T2</sub> High level value on-state slope resistance	11.04	3.59	3.37	mΩ	(I > π × I <sub>T(AV)</sub> ), @ T <sub>J</sub> max.
V <sub>TM</sub> Maximum on-state voltage drop	2.68	1.65	1.57	V	I <sub>pk</sub> = 150A, T <sub>J</sub> = 25°C t <sub>p</sub> = 400μs single junction
di/dt Max. non-repetitive rate of rise of turned on current	150			A/μs	T <sub>J</sub> = 25°C, from 0.67 V <sub>DRM</sub> , I <sub>TM</sub> = π × I <sub>T(AV)</sub> , I <sub>g</sub> = 500mA, t <sub>r</sub> < 0.5μs, t <sub>p</sub> > 6μs
I <sub>H</sub> Max. holding current	200			mA	T <sub>J</sub> = 25°C, anode supply = 6V, resistive load, gate open circuit
I <sub>L</sub> Max. latching current	400				T <sub>J</sub> = 25°C, anode supply = 6V, resistive load

**Blocking**

Parameter	53MT.K 52MT.K 51MT.K	93MT.K 92MT.K 91MT.K	113MT.K 112MT.K 111MT.K	Units	Conditions
V <sub>INS</sub> RMS isolation voltage	4000			V	T <sub>J</sub> = 25°C all terminal shorted f = 50Hz, t = 1s
dv/dt Max. critical rate of rise of off-state voltage (*)	500			V/μs	T <sub>J</sub> = T <sub>J</sub> max., linear to 0.67 V <sub>DRM</sub> , gate open circuit

(\*) Available with dv/dt = 1000V/ms, to complete code add S90 i.e. 113MT160KBS90.

**Triggering**

Parameter	53MT.K 52MT.K 51MT.K	93MT.K 92MT.K 91MT.K	113MT.K 112MT.K 111MT.K	Units	Conditions	
P <sub>GM</sub> Max. peak gate power	10			W	T <sub>J</sub> = T <sub>J</sub> max.	
P <sub>G(AV)</sub> Max. average gate power	2.5					
I <sub>GM</sub> Max. peak gate current	2.5			A		
-V <sub>GT</sub> Max. peak negative gate voltage	10			V		
V <sub>GT</sub> Max. required DC gate voltage to trigger	4.0			V	T <sub>J</sub> = -40°C	
	2.5				T <sub>J</sub> = 25°C	Anodesupply=6V, resistiveload
	1.7				T <sub>J</sub> = 125°C	
I <sub>GT</sub> Max. required DC gate current to trigger	270			mA	T <sub>J</sub> = -40°C	
	150				T <sub>J</sub> = 25°C	Anodesupply=6V, resistiveload
	80				T <sub>J</sub> = 125°C	
V <sub>GD</sub> Max. gate voltage that will not trigger	0.25			V	@ T <sub>J</sub> = T <sub>J</sub> max., rated V <sub>DRM</sub> applied	
I <sub>GD</sub> Max. gate current that will not trigger	6			mA		

**Thermal and Mechanical Specifications**

Parameter	53MT.K 52MT.K 51MT.K	93MT.K 92MT.K 91MT.K	113MT.K 112MT.K 111MT.K	Units	Conditions
T <sub>J</sub> Max. junction operating temperature range	-40 to 125			°C	
T <sub>stg</sub> Max. storage temperature range	-40 to 125			°C	
R <sub>thJC</sub> Max. thermal resistance, junction to case	0.18	0.14	0.12	K/W	DC operation per module
	1.07	0.86	0.70		DC operation per junction
	0.19	0.15	0.12		120° Rect conduction angle per module
	1.17	0.91	0.74		120° Rect conduction angle per junction
R <sub>thCS</sub> Max. thermal resistance, case to heatsink	0.03			K/W	Per module Mounting surface smooth, flat an greased
T Mounting torque ± 10%	to heatsink	4 to 6		Nm	A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound. Lubricated threads.
	to terminal	3 to 4			
wt Approximate weight	225			g	

## 53-93-113MT..KPbF Series

Bulletin I27219 03/06

International  
**IR** Rectifier

### ΔR Conduction (per Junction)

(The following table shows the increment of thermal resistance  $R_{thJC}$  when devices operate at different conduction angles than DC)

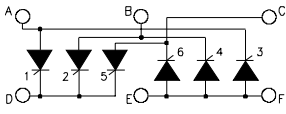
Devices	Sinusoidal conduction @ $T_J$ max.					Rectangular conduction @ $T_J$ max.					Units
	180°	120°	90°	60°	30°	180°	120°	90°	60°	30°	
53/52/51MT.K	0.072	0.085	0.108	0.152	0.233	0.055	0.091	0.117	0.157	0.236	K/W
93/92/91MT.K	0.033	0.039	0.051	0.069	0.099	0.027	0.044	0.055	0.071	0.100	
113/112/111MT.K	0.027	0.033	0.042	0.057	0.081	0.023	0.037	0.046	0.059	0.082	

### Ordering Information Table

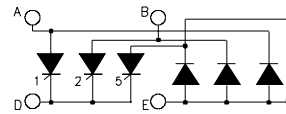
**Device Code**

11	3	MT	160	K	S90	PbF
①	②	③	④	⑤	⑥	

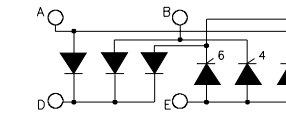
- 1** - Current rating code: 5 = 55 A (Avg)  
9 = 90 A (Avg)  
11 = 110 A (Avg)
- 2** - Circuit configuration code: 3 = Full-controlled bridge  
2 = Positive half-controlled bridge  
1 = Negative half-controlled bridge
- 3** - Essential part number
- 4** - Voltage code: Code x 10 =  $V_{RRM}$  (See Voltage Ratings Table)
- 5** - Critical dv/dt: None = 500V/μs (Standard value)  
S90 = 1000V/μs (Special selection)
- 6** - PbF = Lead-Free



full-controlled bridge  
(53, 93, 113MT..K)



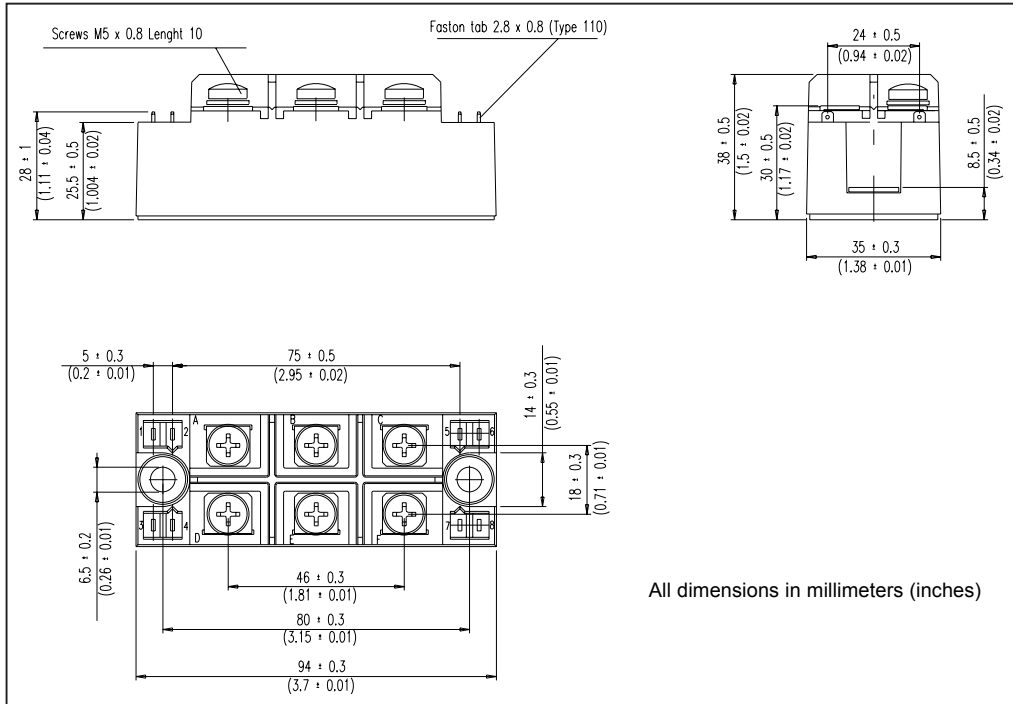
positive half-controlled bridge  
(52, 92, 112MT..K)



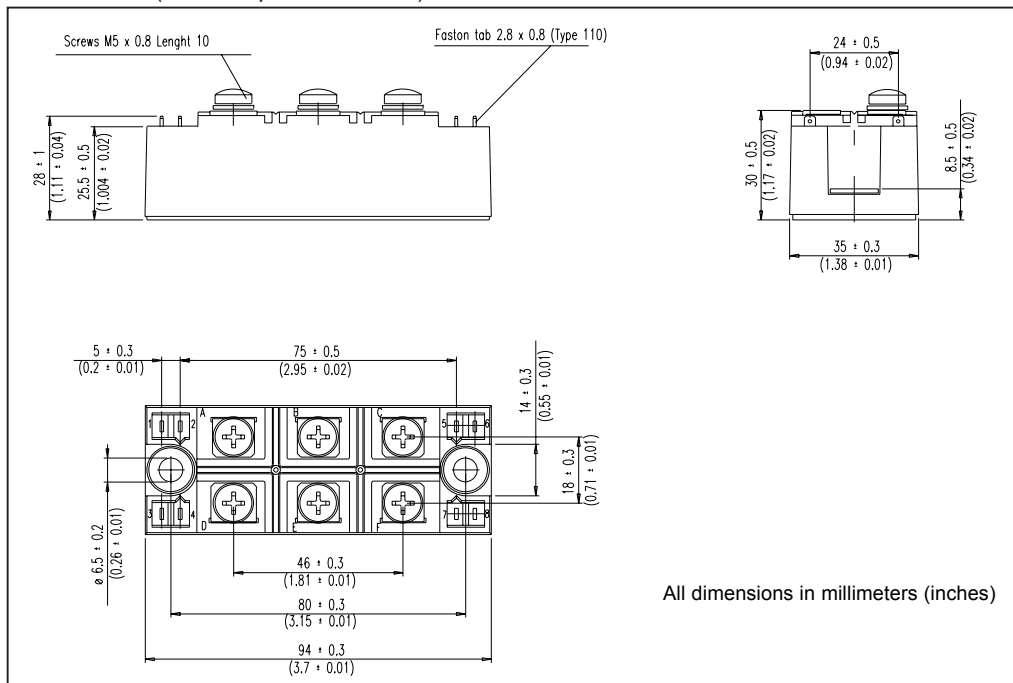
negative half-controlled bridge  
(51, 91, 111MT..K)

**NOTE: To order the Optional Hardware see Bulletin I27900**

Outline Table (with optional barriers)



Outline Table (without optional barriers)



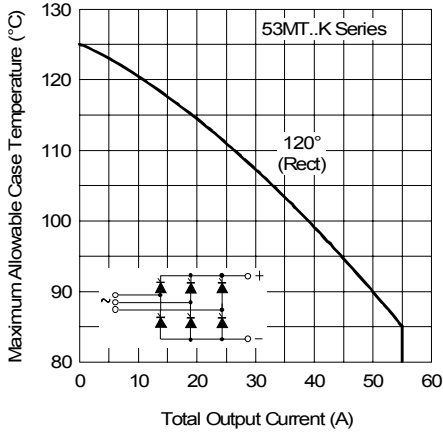


Fig. 1 - Current Ratings Characteristic

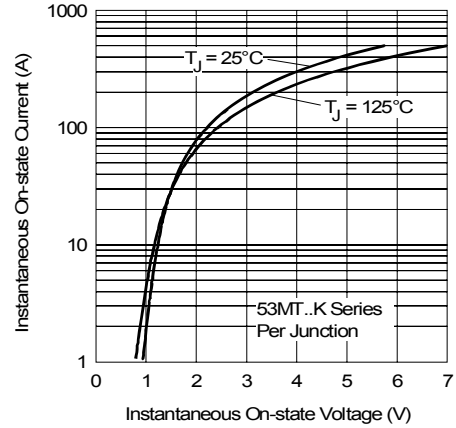


Fig. 2 - Forward Voltage Drop Characteristics

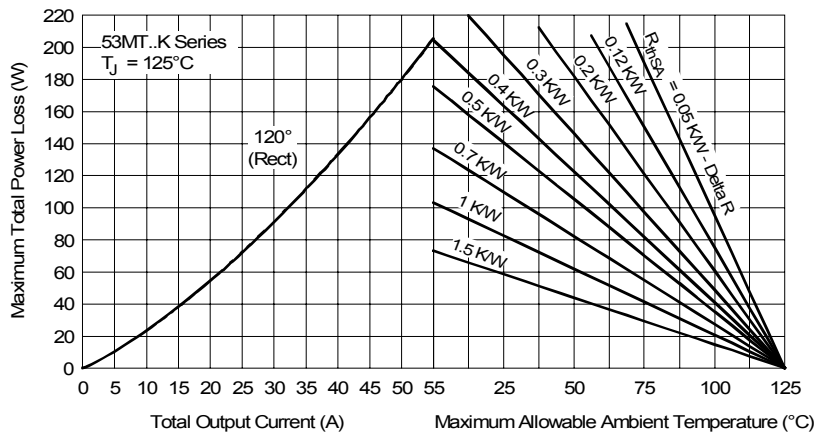


Fig. 3 - Total Power Loss Characteristics

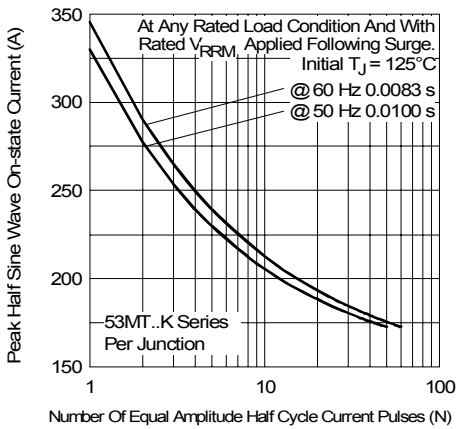


Fig. 4 - Maximum Non-Repetitive Surge Current

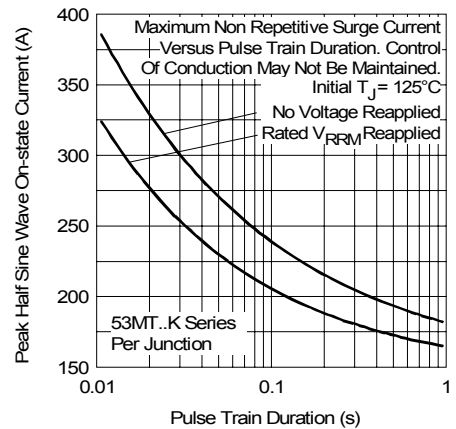


Fig. 5 - Maximum Non-Repetitive Surge Current

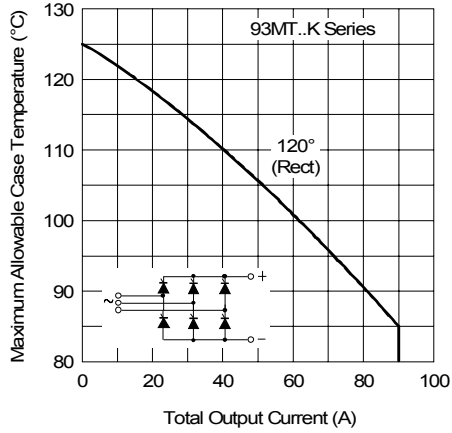


Fig. 6 - Current Ratings Characteristic

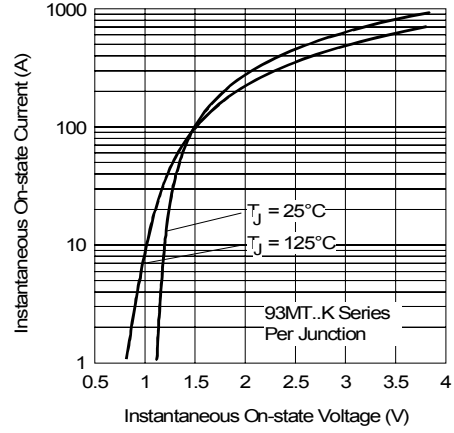


Fig. 7 - Forward Voltage Drop Characteristics

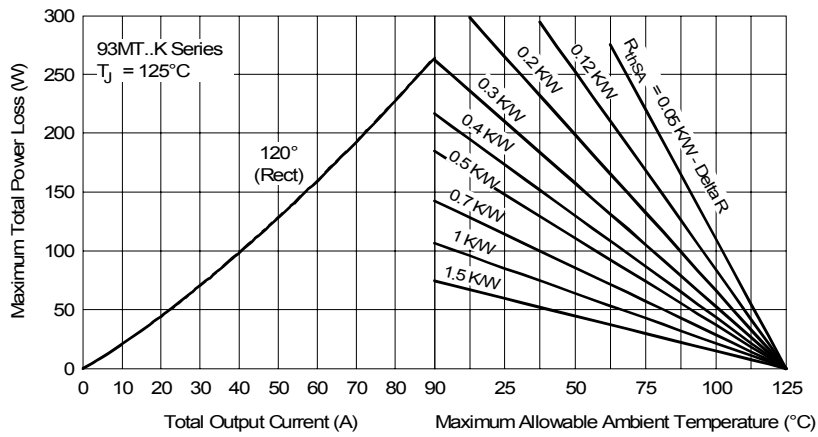


Fig. 8 - Total Power Loss Characteristics

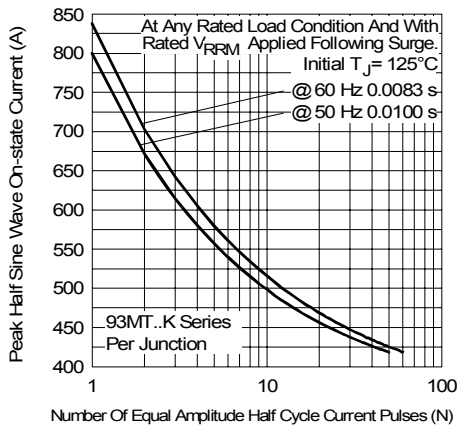


Fig. 9 - Maximum Non-Repetitive Surge Current

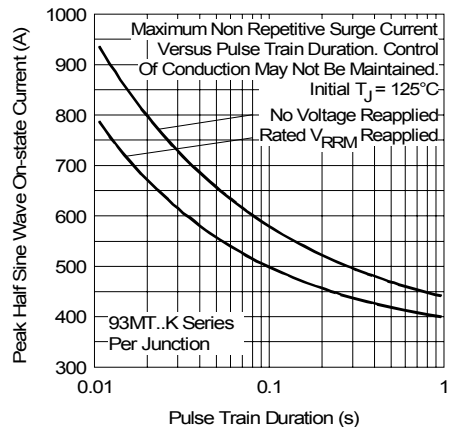


Fig. 10 - Maximum Non-Repetitive Surge Current

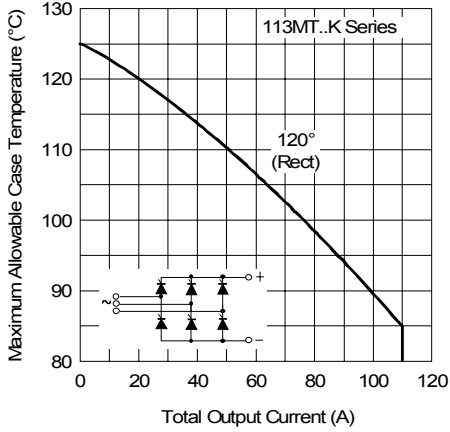


Fig. 11 - Current Ratings Characteristic

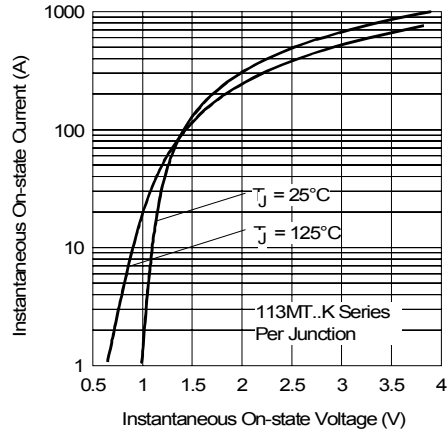


Fig. 12 - Forward Voltage Drop Characteristics

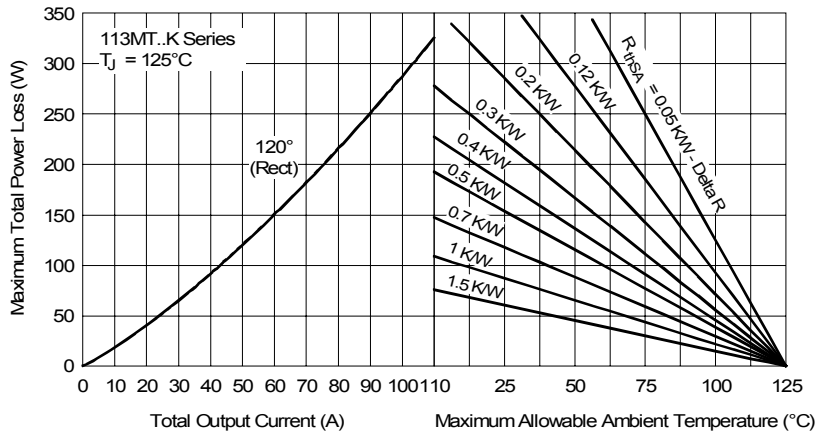


Fig. 13 - Total Power Loss Characteristics

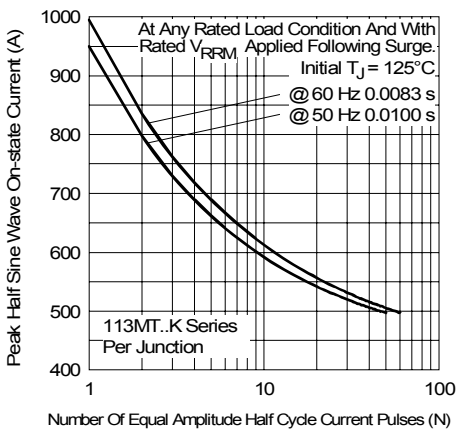


Fig. 14 - Maximum Non-Repetitive Surge Current

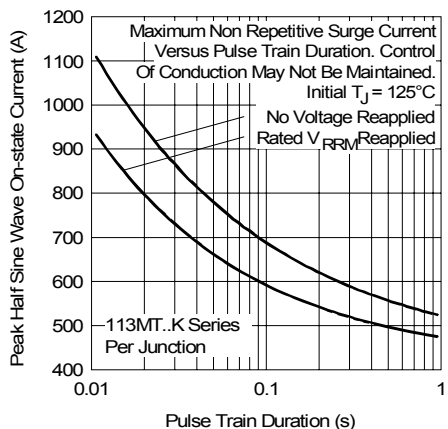


Fig. 15 - Maximum Non-Repetitive Surge Current

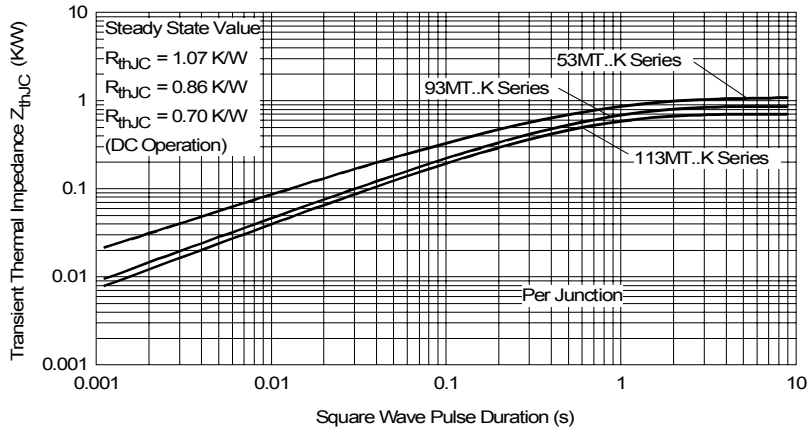


Fig. 16 - Thermal Impedance  $Z_{thJC}$  Characteristics

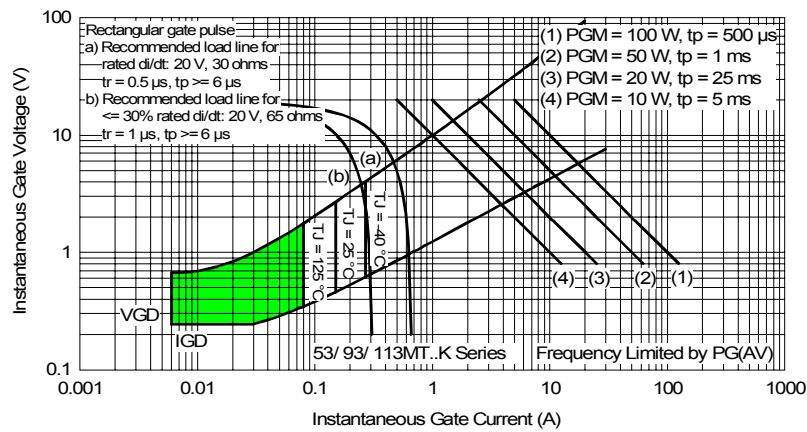


Fig. 17 - Gate Characteristics

Data and specifications subject to change without notice.  
 This product has been designed and qualified for Industrial Level and Lead-Free.  
 Qualification Standards can be found on IR's Web site.